

ABSTRACT OF THE DISCLOSURE

A substrate with a plurality of semiconductor chips mounted thereon is set in a die. The die is then clamped. The die thus clamped forms a space, into which resin is introduced. In doing so, a member is provided to
5 fill a gap between an upper surface of each chip and the die. The member is elastic and thus elastically deforms when the die is clamped. Thus from the elastic member to each chip's upper surface a substantially uniform pressure is exerted. The elastic member is a film extending substantially
10 parallel to each chip's upper surface and contacts the upper surface as the member is tensioned in its in-plane direction. The above resin introduction step can prevent the semiconductor chip from having an upper surface with resin flash.